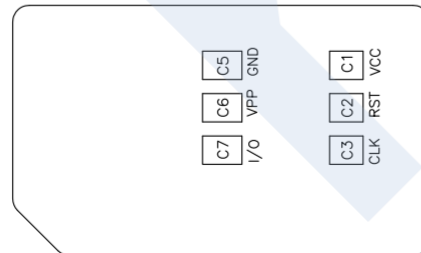
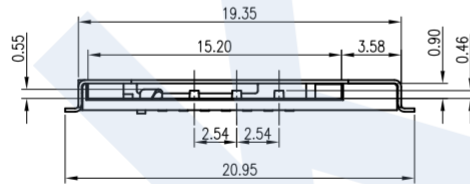
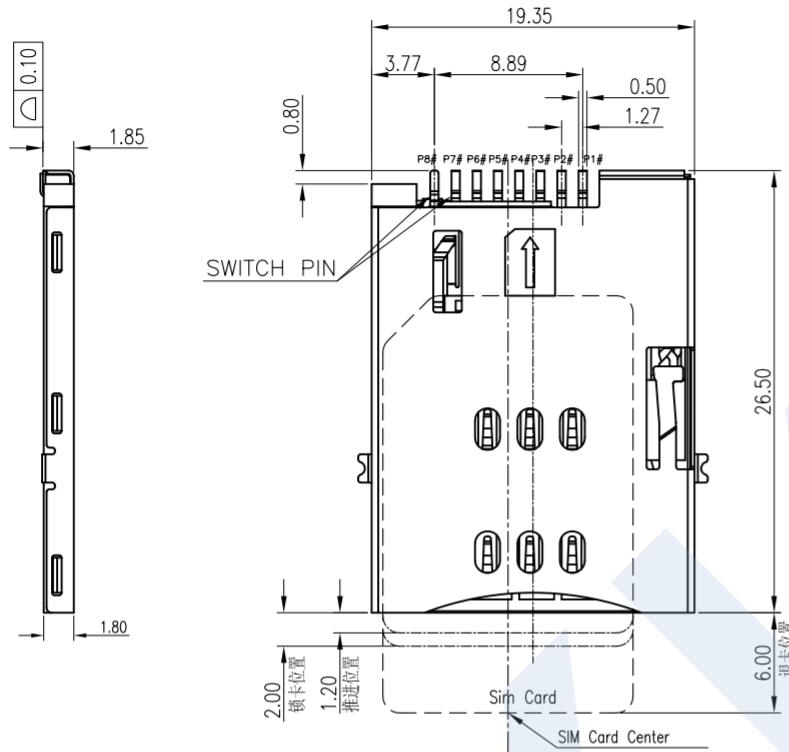
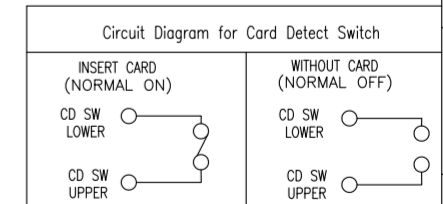
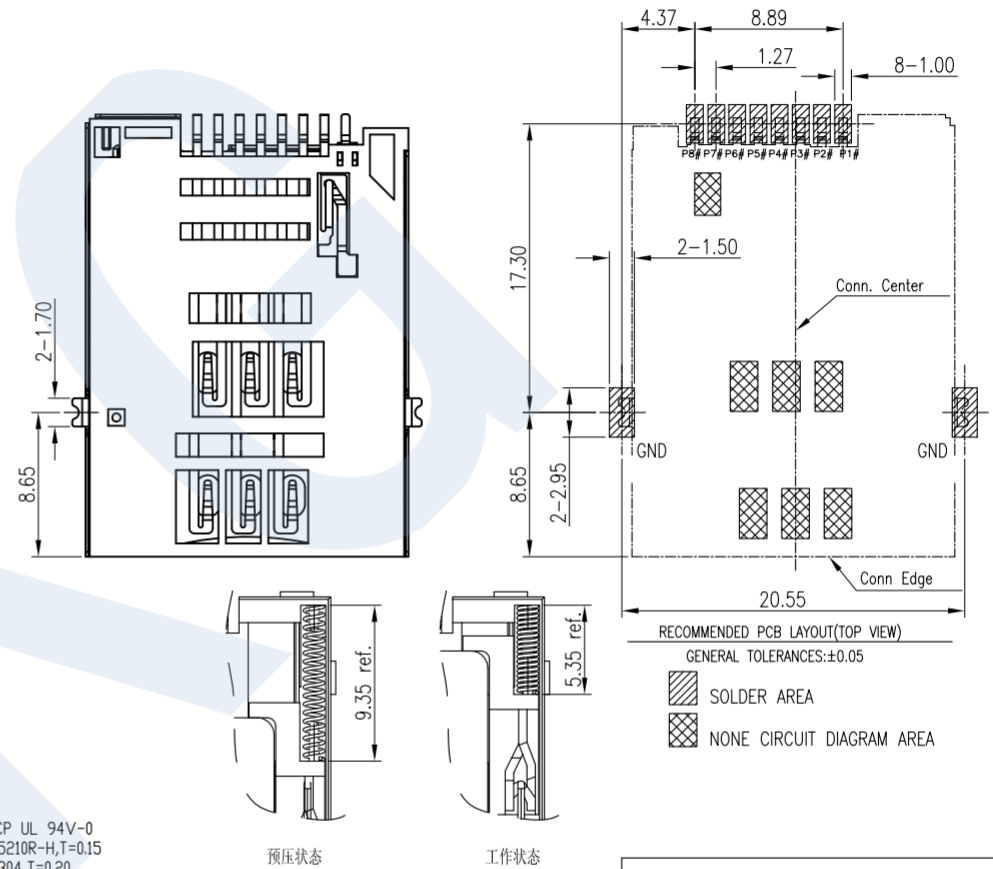


REV.	ECN	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A		NEW RELEASE	2016.03.09	Yang		WEI



PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET

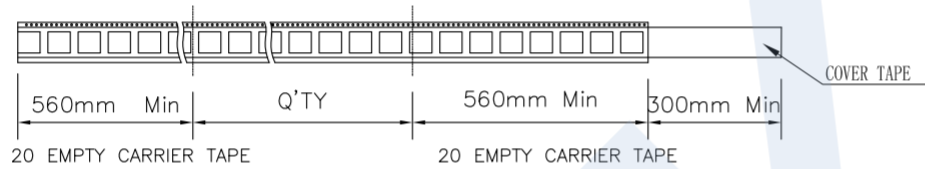
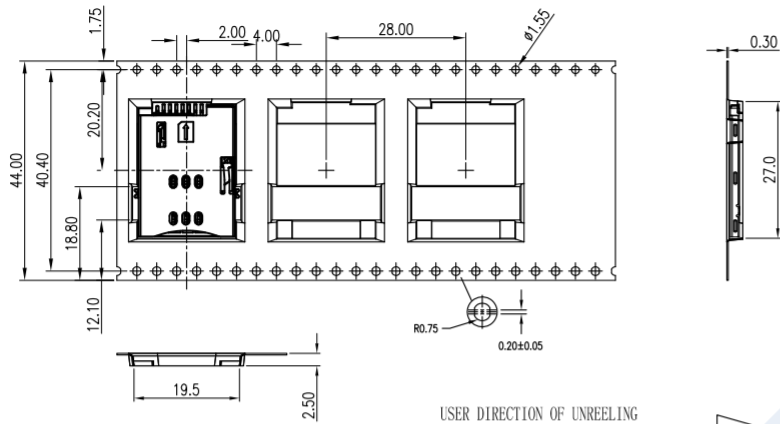
NOTES:
 1) MATERIAL:
 HOUSING: LCP UL 94V-0
 CONTACT: C5210R-H,T=0.15
 SHELL: SUS304,T=0.20
 MYLAR: POLYESTER
 2) FINISH:
 CONTACT: GOLD FLASH PLATED ON CONTACT AREA;
 GOLD FLASH PLATING ON SOLDER TAILS, WITH
 ENTIRE CONTACT UNDERPLATED 50μm Min. NICKEL
 SHELL: 50μm Min. NICKEL UNDERPLATED OVERALL,
 GOLD FLASH PLATED ON SOLDER TAILS
 3) INFRARED REFLOW SOLDERING: 10sec. Min. at 260±10



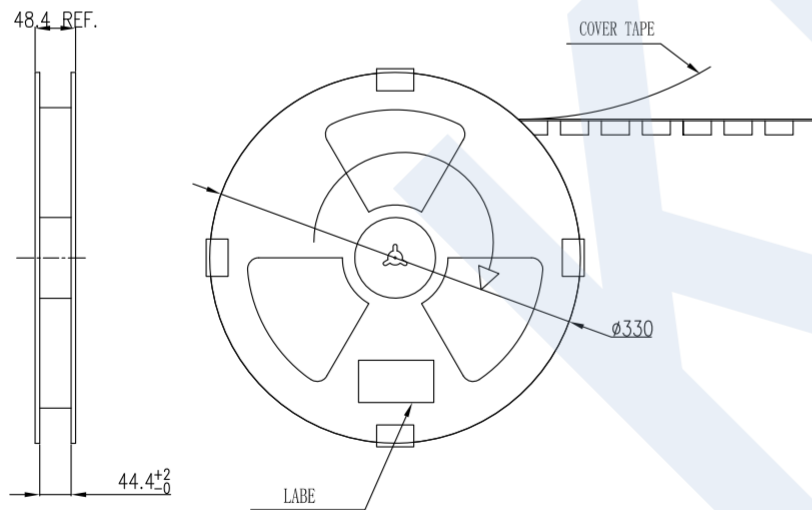
MILLIMETERS	INCH	UNITS	MM		
X° ± 2°	X° ±	MAT'L			
.X ± 0.30	.XX ±	SEE NOTES		PART NUMBER:	TITLE:
.XX ± 0.25	.XXX ±	FINISH		APPD: WEI	SIM card 6+2 pin push H1.8
.XXX ± 0.15	.XXXX ±	SEE NOTES		CHKD:	DWG NO.:
		QTY		DR: Yang	
		SEE NOTES			

SCALE	SHEET	REV.
1:1	1/2	A0

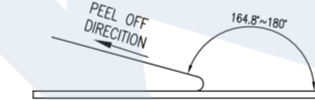
1



2



COVER TAPE PEELING FORCE: 20gf~120gf



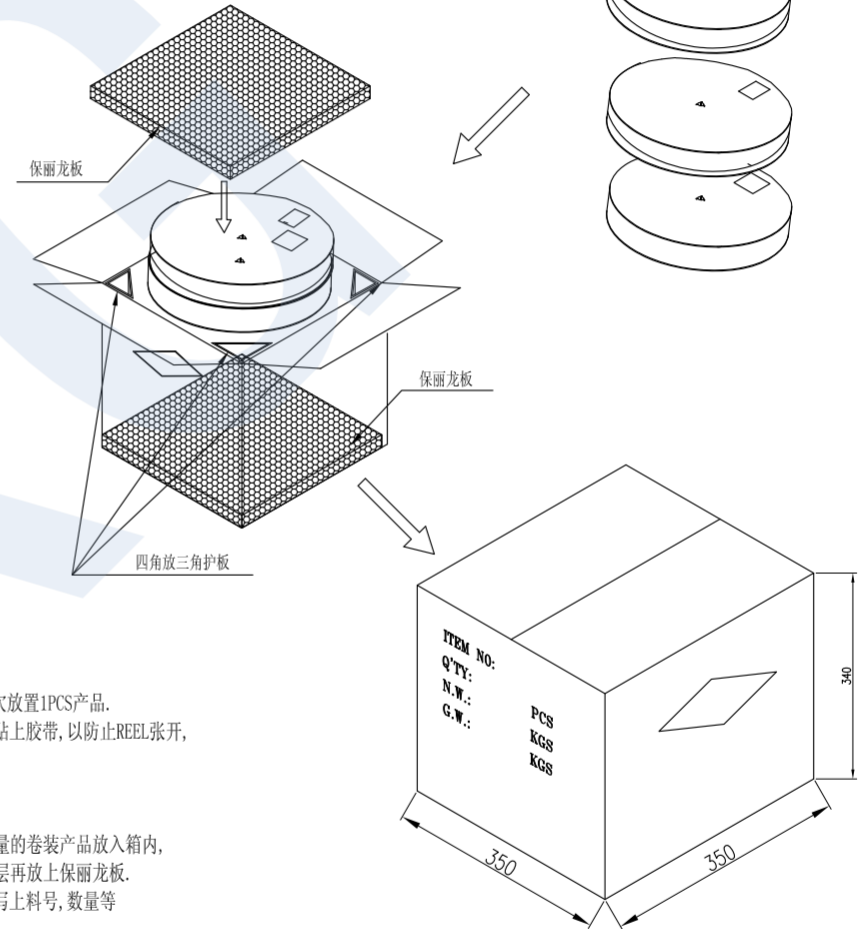
NOTE:


- 1.依<图一>示放置产品于下载中,每穴放置1PCS产品.
- 2.包装机包好后,在REEL的个等分点贴上胶带,以防止REEL张开,每REEL贴1PCS标签,如<图二>示
- 3.包装数量见如<TABLE 1>示
- 4.包装成箱见如<图三>示
箱底放保丽龙板,再依次将指定数量的卷装产品放入箱内,四角分别放入四个三角护板,最上层再放上保丽龙板.
- 5.封箱,在封好的纸箱上按客户要求写上料号,数量等

<TABLE 1> PACKAGING QUANTITY

QTY/REEL	REEL/CARTON	QTY/CARTON
550	6	3300

<图三>



MILLIMETERS	INCH	UNITS	MM		
X° ± 2°	X° ± 2°	MAT'L			
.X ± 0.30	.XX ± 0.012	SEE NOTES		PART NUMBER:	TITLE: SIM PUSH 6+2PIN H1.8 包装规范
.XX ± 0.20	.XXX ± 0.008	FINISH		APPD: Sean	DWG NO.:
.XXX ± 0.10	.XXXX ± 0.004	SEE NOTES		CHKD:	
		QTY		DR: Yang	
		SEE NOTES			